



TH97/2478





TH09/2479

IATF 0113686 SGS TH07/1033

D20XB20 - D20XB60

PRV: 200 - 600 Volts

lo: 20 Amperes

FEATURES:

- * High current capability
- * High surge current capability
- * High reliability
- * Low reverse current
- * Low forward voltage drop
- * High case dielectric strength of 2000 V_{AC} @1 Sec
- * Ideal for printed circuit board
- * Very good heat dissipation
- * Pb / RoHS Free

MECHANICAL DATA:

* Case : Reliable low cost construction
utilizing molded plastic technique

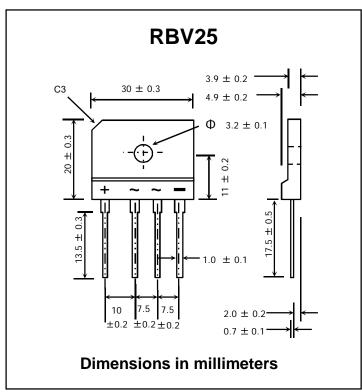
* Case : Reliable low cost construction

* Epoxy : UL94V-0 rate flame retardant* Terminals : Plated lead solderable per

MIL-STD-202, Method 208 guaranteed Polarity: Polarity symbols marked on case

Mounting position : AnyWeight : 7.7 grams

SILICON BRIDGE RECTIFIERS



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified

RATING	SYMBOL	D20XB20	D20XB60	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	200	600	V
Maximum RMS Voltage	VRMS	140	420	V
Maximum DC Blocking Voltage	VDC	200	600	V
Maximum Average Forward Current (50Hz Sine wave, R-load)	lo	20 (With heatsink, Tc = 87°C) 3.5 (Without heatsink, Ta = 25°C)		А
Maximum Peak Forward Surge Current, Tj = 25°C (50Hz sine wave, Non-repetitive 1 cycle peak value)	IFSM	240		А
Current Squared Time at 1ms ≤ t < 10 ms, Tc=25°C	I ² t	200		A ² S
Maximum Forward Voltage per Diode at IF = 10 A	VF	1.1		V
Maximum DC Reverse Current, VR=VRRM (Pulse measurement, Rating of per diode)	lR	10		μА
Maximum Thermal Resistance, Junction to case	RθJC	1.5 (With heatsink)		°C/W
Maximum Thermal Resistance, Junction to Ambient	RθJA	22 (Without heatsink)		°C/W
Operating Junction Temperature	TJ	150		°C
Storage Temperature Range	Тѕтс	- 40 to + 150		°C

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RATING AND CHARACTERISTIC CURVES (D20XB20 - D20XB60)

FIG.1 - DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

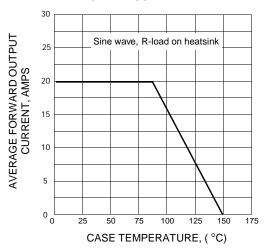


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

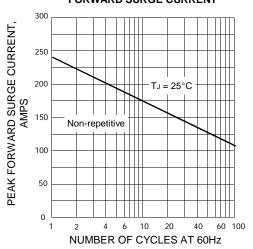


FIG.3 - TYPICAL FORWARD CHARACTERISTICS PER DIODE

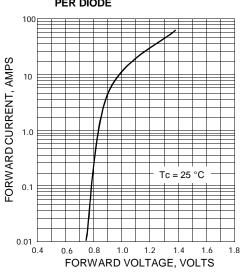
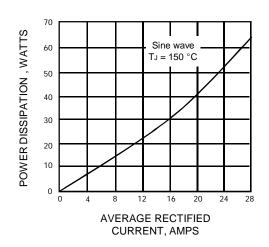


FIG.4 - POWER DISSIPATION



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